

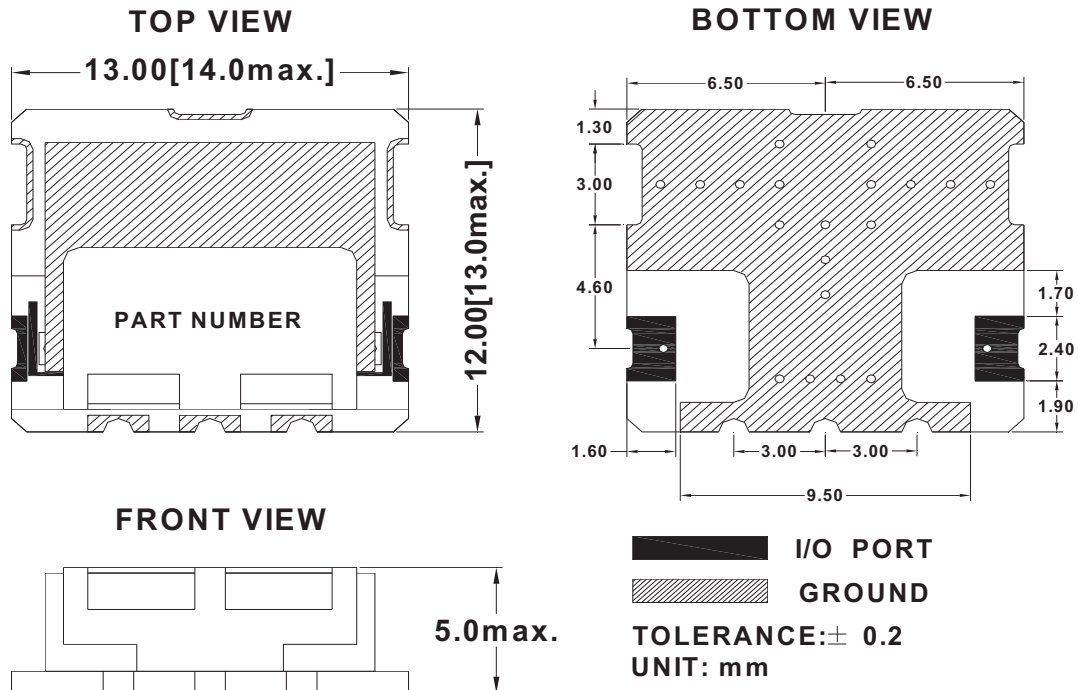
SPECIFICATION



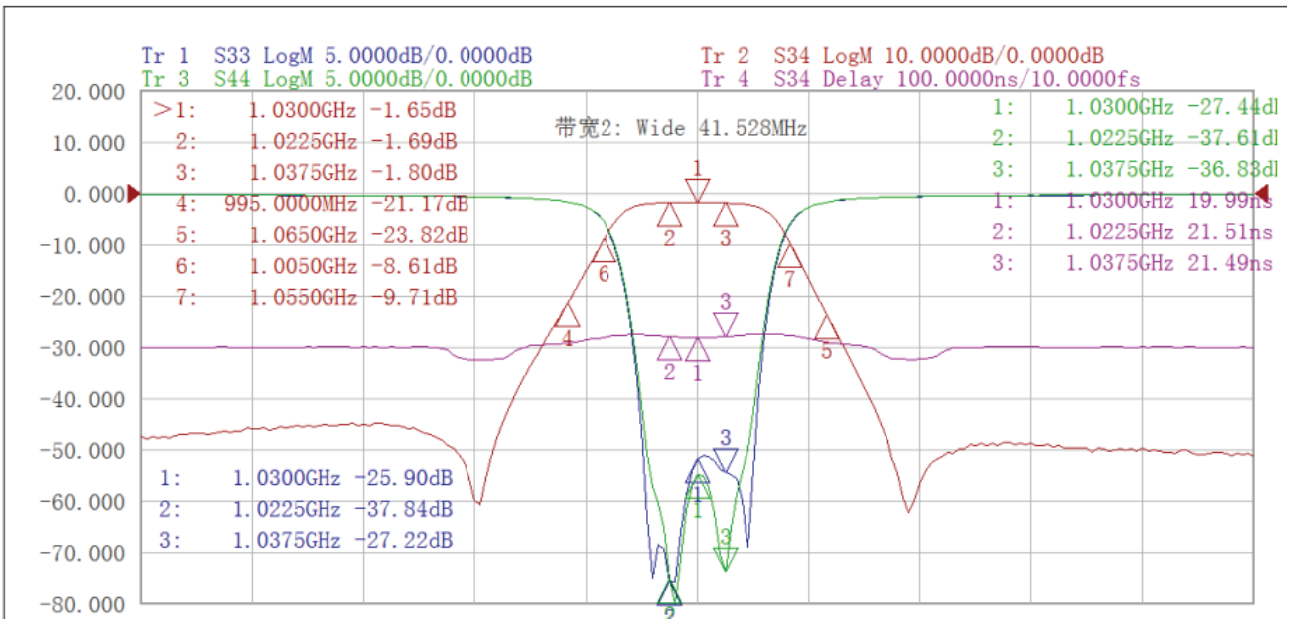
Written by	Checked by	Approval
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ELECTRICAL SPECIFICATIONS			
ITEM	SPEC	UNIT	
1	Center Frequency [fo]	1030.0	MHz
2	Bandwidth [3dB BW]	$fo \pm 7.5$ [1022.5 ~ 1037.5]	MHz
3	Insertion Loss in BW	3.0 max(in regular temp)	dB
4	Ripple in BW	1.0 max(in regular temp)	dB
5	V.S.W.R in BW	1.5 max(in regular temp)	Ratio
6	Attenuation	20.0 min. @ $fo \pm 35.0$ [995.0 & 1065.0] MHz 5.0 min. @ $fo \pm 25.0$ [1005.0 & 1055.0] MHz	dB
7	Group Delay	25.0 max	ns
8	In/Out Impedance	50.0	Ω
9	Operation Temperature Range	-40°C to +70°C	°C

MECHANICAL SPECIFICATIONS



PERFORMANCE



SOLDERING CONDITION

REFLOW SOLDERING STANDARD CONDITION

1. Please ensure that it is a good ground area between GROUND and I/O PORT when you solder the product. In order to have a good grounding, please fix welding side pin at the bottom after reflow soldering.
2. The below is recommended reflow temperature curve. Due to different substrate and reflow soldering equipment, actual temperature curve is confirmed by case.
3. If it occurs to need manual soldering, the temperature should be 350°C, but not over 3 times, and reflow and manual soldering should not be over 3 times.
4. Soldering can only be for PCB packaging product. It is forbidden for ceramic dielectric product.

